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(21) International Application Number: PCT/US96/12761 (22) International Filing Date: 9 August 1996 (09.08.96) (30) Priority Data: 08/514,049 11 August 1995 (11.08.95) US 08/644,911 28 May 1996 (28.05.96) US (71)(72) Applicant and Inventor: KIRSTEN, Kenneth, J. [US/US]; 675 B Streamwood Boulevard, Streamwood, IL 60107 (US). (74) Agent: GEORGES, Peter, J.; Breneman & Georges, 3150 Commonwealth Avenue, Alexandria, VA 22305 (US).		(81) Designated States: JP, KR, SG, European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE). Published With international search report.
(54) Title: EPOXY RESIN BASED SOLDER PASTE (57) Abstract A method of making low and high mass assemblies at surface mount profile conditions utilizing a solder paste have a binder comprised of a thermosetting resin and cross-linking agent that also acts as a flux is described. The method of selecting the components and specific binders, including binders with a catalyst such as tin octoate are also described. The binder utilized has a gel point that is at or above the melting point of the solder powder and most preferably above such melting point.		